Company Presentation

May 2011

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which are explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

Content

I. Executive Summary

II. Products and Markets

III. Growth Opportunities

IV. Financials

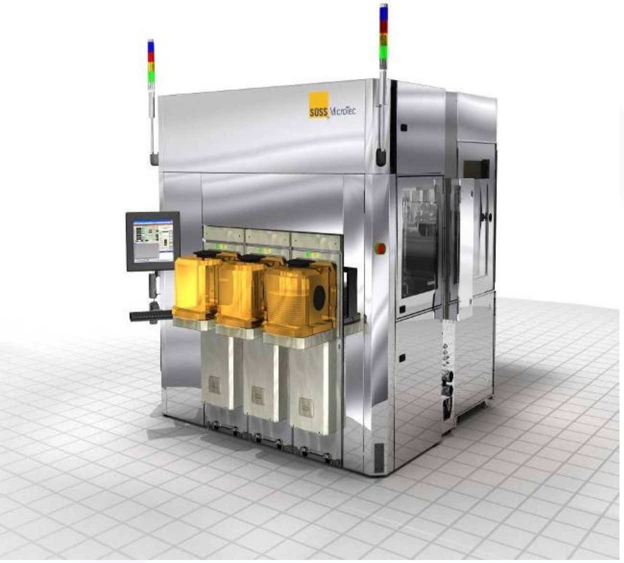
V. Outlook

VI. Appendix

SUSS MicroTec Spotlight

- SUSS MicroTec: A global leader in semiconductor equipment
- Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- We are focused on high growth market segments:

  Semiconductors, MEMS, LEDs



Key Data*:

- Bloomberg Symbol: SMH
- TecDax
- Share price: 11,73 €
- Market Cap: 220 Mio. €
- Enterprise Value: 185 Mio. €

* April 29, 2011

SUSS MicroTec Key Information

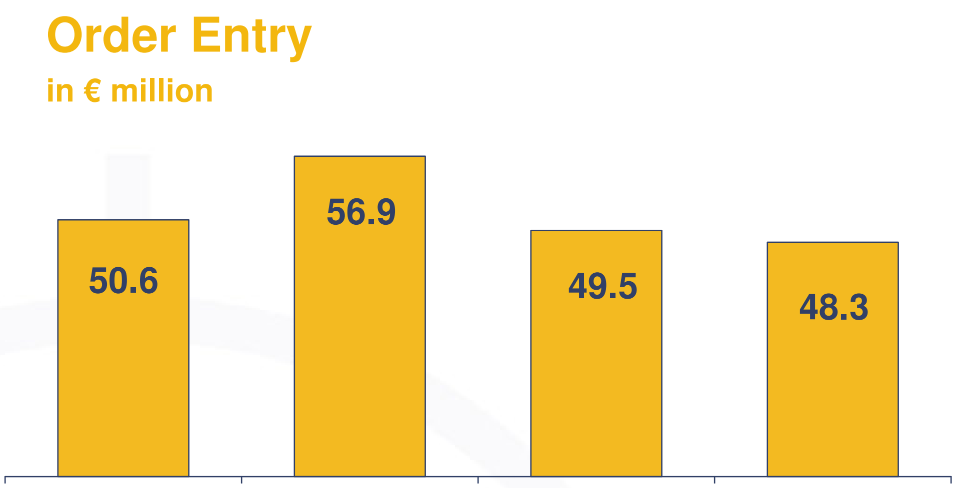
Key figures 2010:

- Order entry: 189.3 million €
- Sales: 139.1 million €
- EBIT: 14.3 million €
- Free Cash Flow: 14.1 million €
- More than 8,000 systems installed worldwide

Major Milestones:

- Outstanding growth in order entry
- Double digit EBIT-margin
- Major reorganization and site consolidation for increased efficiency and lean cost structures
- Listed in TecDAX (Top 30 Germany technology companies)

12 Months Business Development

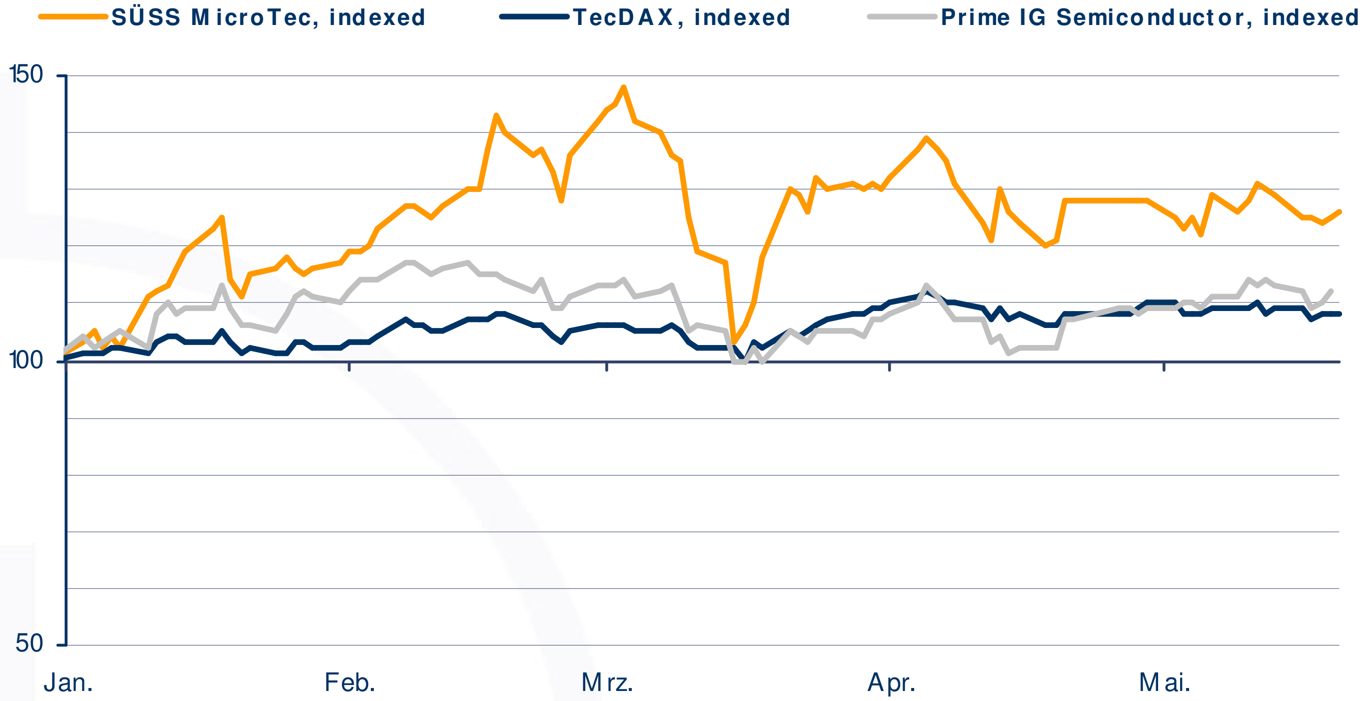


Order Entry over the
last 12 Months: ~ 205 € million

Sales over the last
12 Months: ~ 150 € million

Stock Performance 2011

(Price of the SUSS MicroTec Share at December 30, 2010: € 9.14)



4 months average daily trading volume: 310,000

Content

SUSS MicroTec In The Value Chain

Equipment Supplier

SUSS MicroTec

ICs & Components

Infineon technologies

ASE INC. KAOHSIUNG

SPIL

SAMSUNG

FUJITSU

STATS

IBM

EPCOS

ANALOG DEVICES

TEXAS INSTRUMENTS

Amkor Technology

End Products

NOKIA Connecting People

SONY

SIEMENS

MOTOROLA

BOSCH

PHILIPS

SAMSUNG

OSRAM Opto Semiconductors

End User

Research Institutes

imec

Fraunhofer IZM

工業技術研究院 Industrial Technology Research Institute

Products and Process Solutions

Products

Mask Track

Mask Aligner

Coater/
Developer

Wafer Bonder

Process Steps

Front-end

Photomask Cleaning

Back-end

Alignment
Exposure
Nano Imprinting

Coating
Developing

Bond Alignment
Permanent Bonding
Temporary Bonding

Segments

Photomask Equipment

Lithography

Substrate Bonder

Mega Trends Driving our Key Markets

Key Markets

Computing

Communication

Entertainment

Transportation

Electronics → **Semiconductors**
- Front End
- Back End

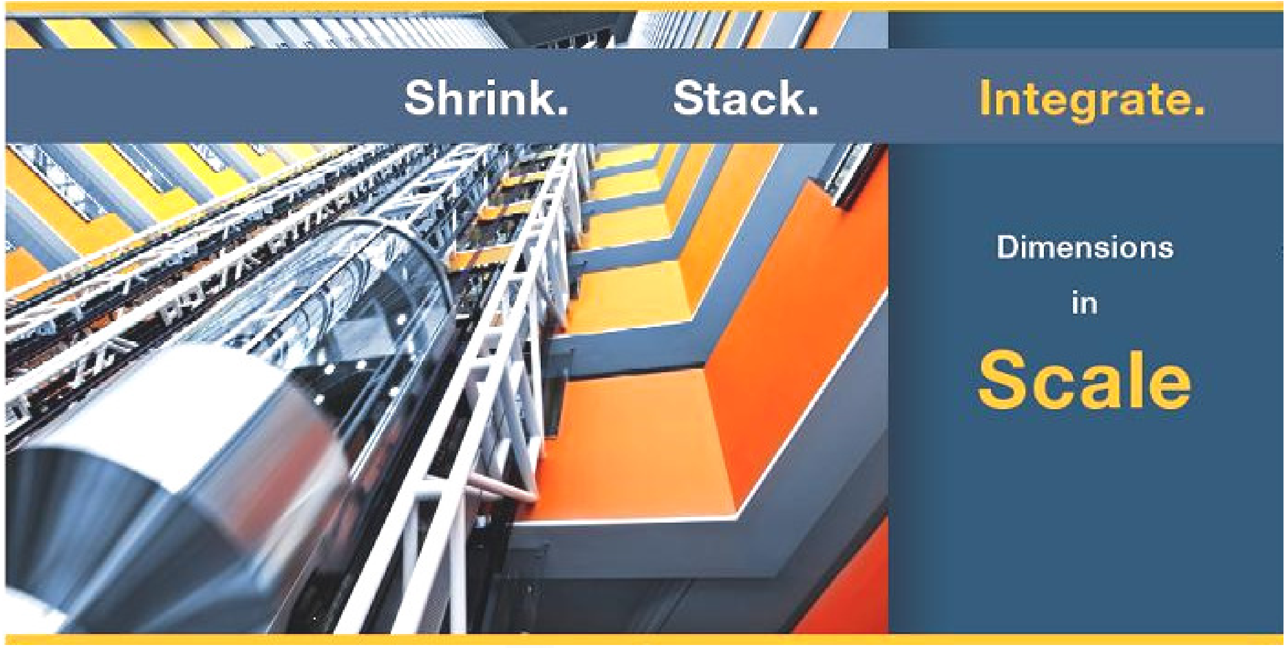
Sensors → **MEMS**

Energy Efficiency

Solid State Lighting → **LED**

Enabling Semiconductor Trends

- SUSS MicroTec drives and enables the fundamental challenges of the semiconductor Industry:

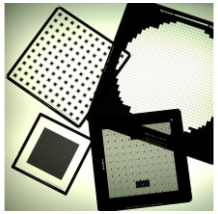


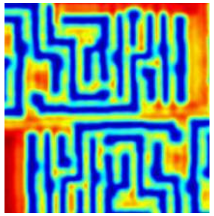
- The SUSS MicroTec family of products provides equipment and process solutions for 2-dimensional and 3-dimensional scaling

Semiconductors

- SUSS MicroTec offers solutions for performance and yield critical steps in semiconductor manufacturing
- Front End: Mask Cleaning
- Back End: Advanced Packaging
  3D Integration

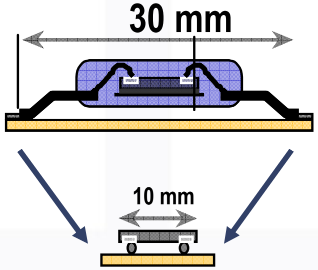
Mask Cleaning

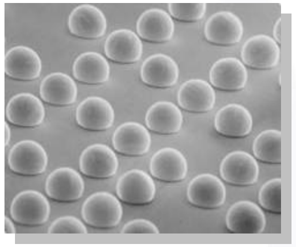




Maintains mask integrity of 193i sub 22nm, EUVL and NIL lithography

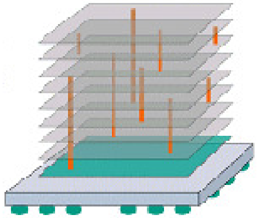
Advanced Packaging

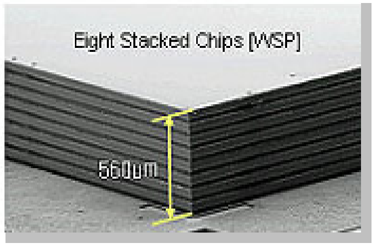




Micro-bumping replaces wire-bonding for high-end integrated circuits

3D Integration





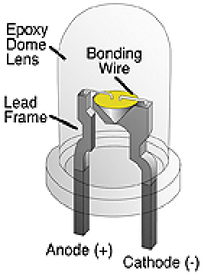
Stacking chips allows for higher device complexity

MEMS and LED

MEMS

- Micromechanical devices with electrical functions
- **M**icro **E**lectro **M**echanical **S**ystems are found in a wide application range from automotive over industrial process control sensors to consumer products

LED

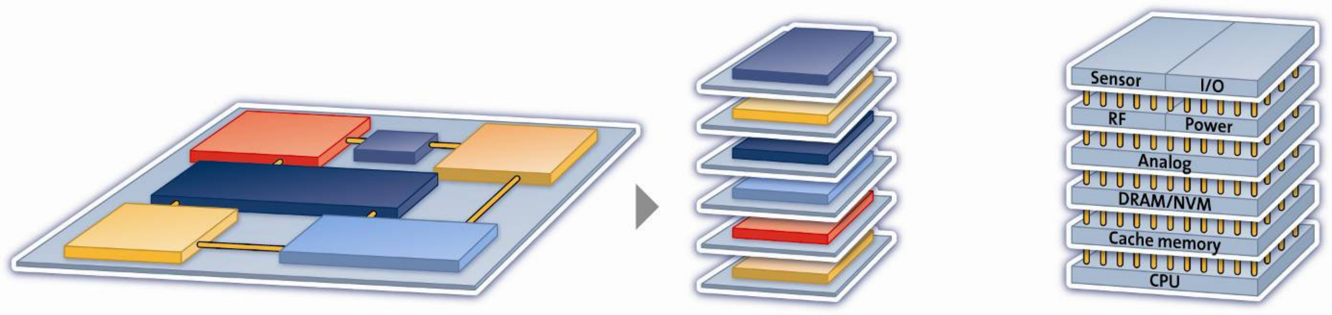


- Ultra High Brightness Light Emitting Diodes (UHB LED) for solid state lighting
- UHB LEDs drive rapidly growing LED markets like automotive, consumer electronics and lighting applications

- For MEMS and LED production SUSS MicroTec offers a comprehensive suite of products: Mask Aligners – Coaters / Developers – Wafer Bonders

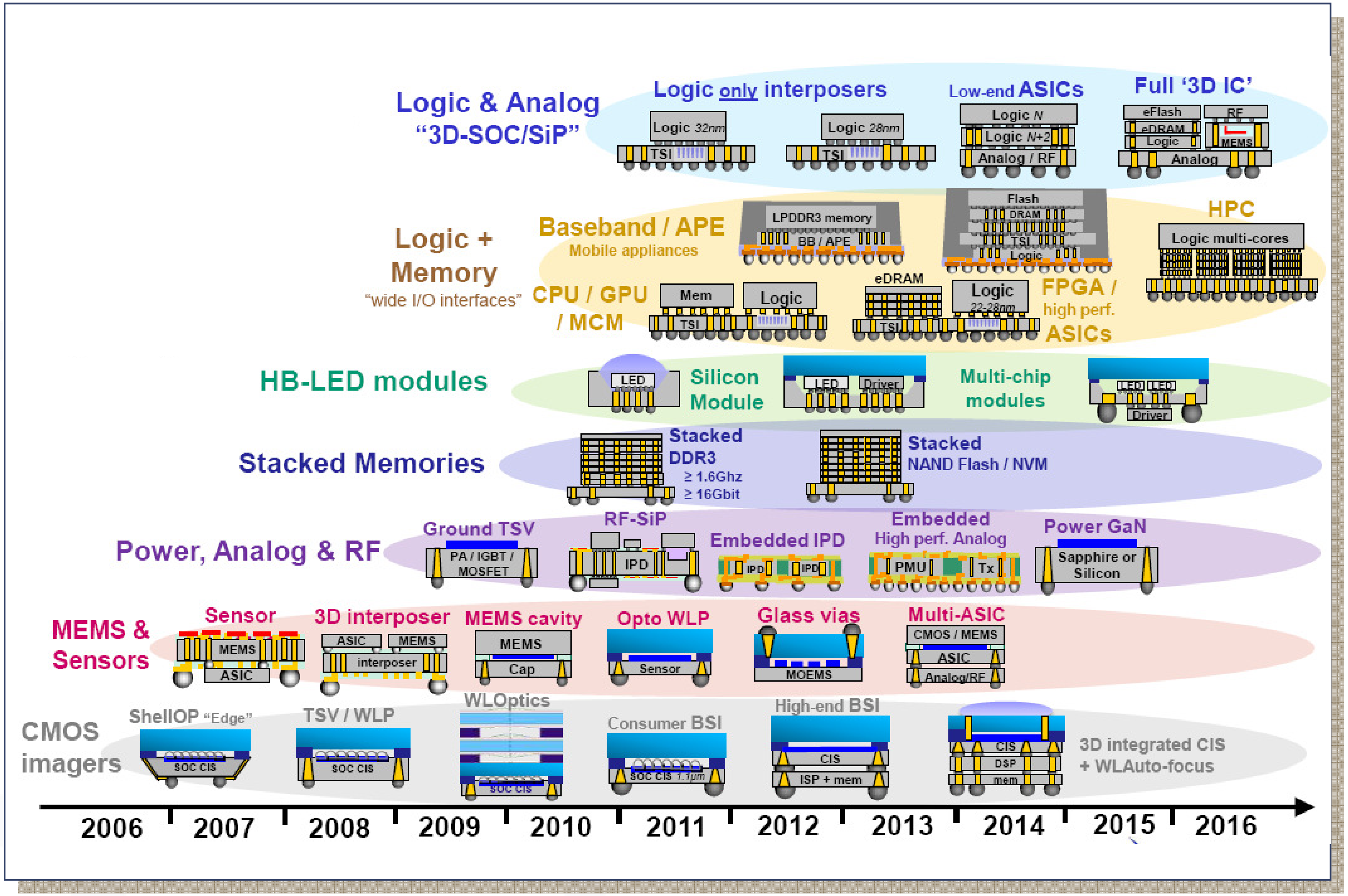
From Advanced Packaging to 3D Integration

- Technical and economical limitations increasingly slow down the shrink roadmap of integrated circuits
- Going into the third dimension by stacking chips allows for a further complexity increase of integrated devices



- 3D integration promises greater space efficiency, lower power consumption and a significant increase in performance.
- SUSS MicroTec develops equipment and processes for 3D Integration

3D Integration: Chip Design Using the Third Dimension

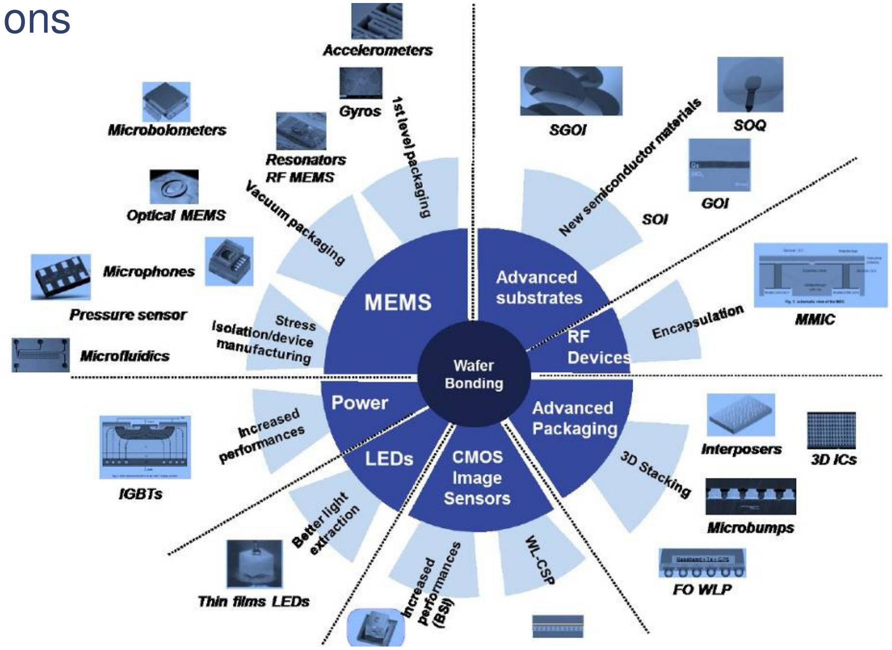


Source: Yole Développement (2010)

Content

Growth Opportunities

- The company’s long term growth perspective derives from the double digit growth rates of the target markets 3D Integration, Advanced Packaging, LED and MEMS
- SUSS MicroTec is one of the leading suppliers for wafer bonders in the semiconductor industry offering a broad portfolio of permanent and temporary bonding equipment and process solutions
- The wafer bonder equipment market is estimated to grow rapidly to a size of larger 500 million $ within the next few years
- SUSS MicroTec targets a market share of 30%+ which is in line with the current market position



Source: Yole Développement

Enabling Growth: Production in Sternenfels

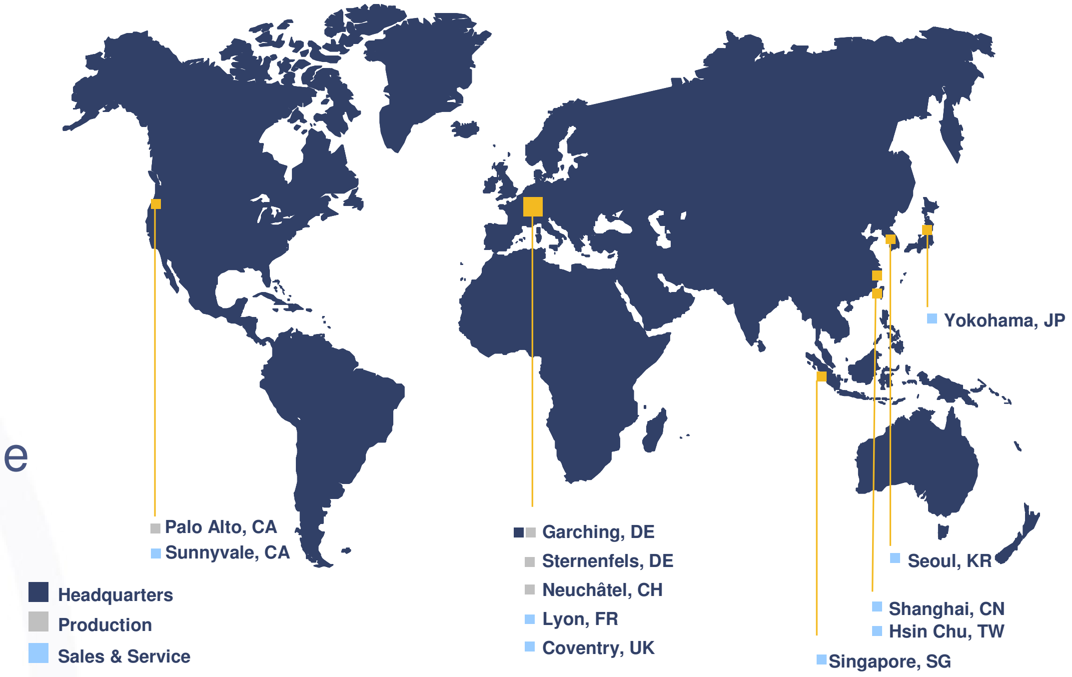
- Three product lines under one roof
  - Photomask Equipment
  - Coater / Developer
  - Bonder
- Synergies in the development and production
- Production facility (15,000 m²) with two large clean rooms
  - Meets modern production and clean room standards
  - Supports anticipated expansion of business

Reduction of development and production sites from existing four in January 2010 to two highly efficient sites in Germany now

Enabling Growth: Differentiation

SÜSS has all it takes to be a global leader

- Strong brand standing for
  - Precision
  - Reliability
  - Longevity
- Technological leadership
- Comprehensive product range
- Global footprint



Content

Key Financials continuing operations

in € million	Q1 2011	Q1 2010	FY 2010	FY 2009
Order Intake	48.3	32.3	189.3	93.3
Order Backlog (end of period)	130.5	75.4	116.1	57.0
Revenue	32.0	21.9	139.1	103.9
EBIT	2.5	-0.1	14.3	2.8
EBIT in % of Sales	*7.8%*	*-0.2%*	*10.3%*	*2.7%*
Earnings after tax	2.4	-0.7	13.0	0.5
EPS in € (basic)	0.13	-0.04	0.71	0.03
Employees	647	579	616	498
Free Cash Flow*	-2.2	-1.3	14.1	8.9
Net Cash**	35.1	11.0	34.6	18.4

* Before consideration of purchase or sale of available-for-sale securities and before consideration of extraordinary items from purchase or sale of subsidiaries

** incl. interest-bearing securities

Content

Outlook

Outlook	+ Strong competitive positioning: first or second in the target markets + Double-digit growth rates in target markets for the years to come + Strong growth potential for the Substrate Bonder Division + Expansion of the solid financial situation and increasing profitability

Guidance	+ FY 2011e:	- Sales of more than 170 € million - EBIT-margin 10% – 15%
	+ H1 2011e:	- Order intake over 80 € million - Sales of approximately 80 € million

SÜSS MicroTec

Investment case

- Strong balance sheet
- Lean cost structure
- Strong fundamental growth in target markets
- Significant mid term revenue opportunity
- Strong competitive positioning: first or second in the target markets
- Evolve from Lithography company to leading company in the semiconductor backend, enabling 3D integration
- Participate in the consolidation of the backend

Content

I. Executive Summary

II. Products and Markets

III. Growth Opportunities

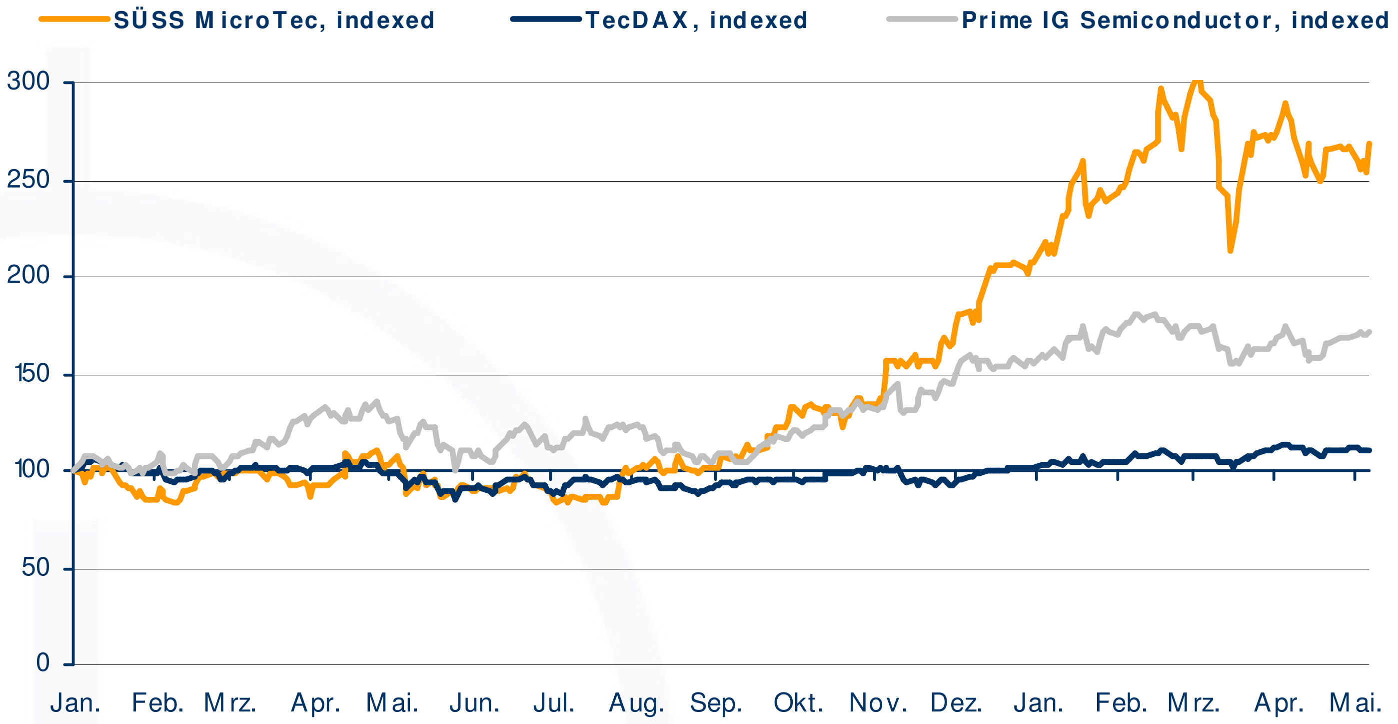
IV. Financials

V. Outlook

VI. Appendix

Long Term Development of the SUSS Share

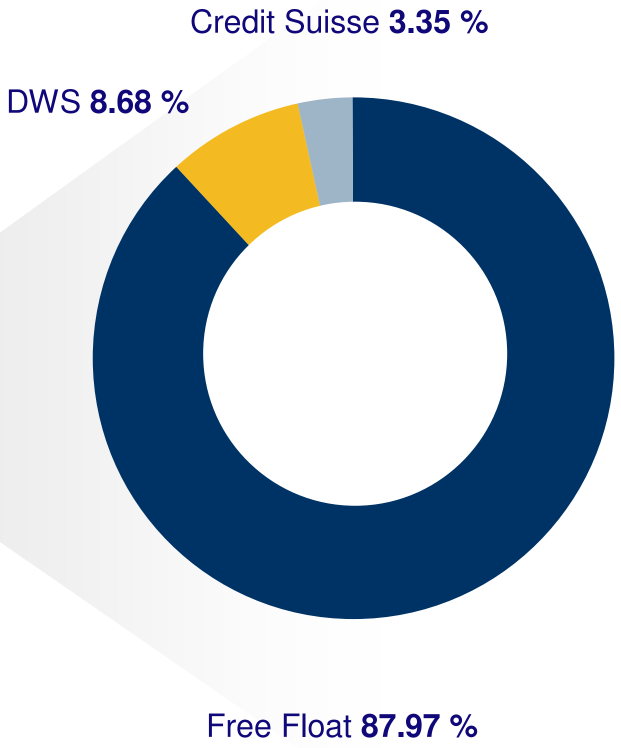
(Price of the SUSS MicroTec Share at January 4, 2010: € 4,40)



Average daily trading volume: ~170,000

Ownership Information

Market Capitalization (04/30/2011)	ca. € 220 million
Bloomberg Symbol	SMH
Reuters Symbol	SMHG
WKN	722670
ISIN	DE0007226706
Number of registered Shares	18,721,038
Stock Category	No-par value shares
Ownership information (04/30/11)	
Stock Market Segment	Prime Standard
Listing	Frankfurt, Regulatory Market
Tradable at	Xetra, Frankfurt, Hamburg, Berlin – Bremen, Dusseldorf, Stuttgart, Munich
Designated Sponsor	Equinet Bank AG Close Brothers Seydler Bank AG
Segment	Semiconductors
Ø Trading Volume per day in 2011	310,000 Shares



Investor Relations Information

Contact

Franka Schielke

Tel.: +49 (0) 89-32007- 161
Fax.: +49 (0) 89-32007- 451
Email: franka.schielke@suss.com

SÜSS MicroTec AG
Schleissheimer Strasse 90
85748 Garching (Munich)
Germany
www.suss.com

Financial Calendar 2011

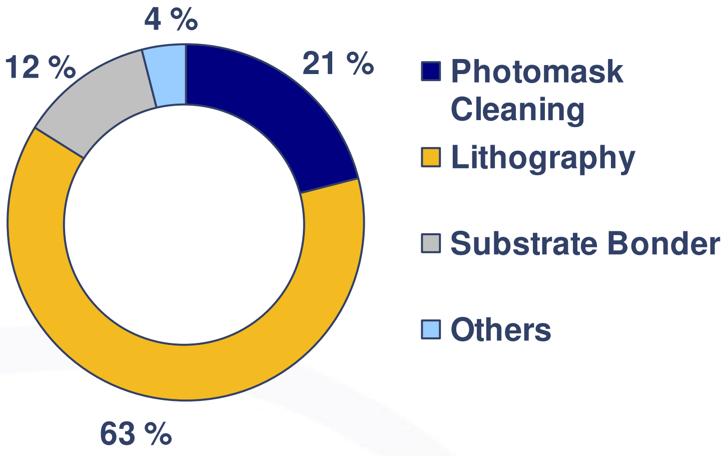
Photonics Conference, Munich	May 24
DZ Bank Sustainable Technologies Conference, Zurich	June 8
UniCredit European Forum, San Francisco	June 8 / 9
Close Brothers Seydler Conference, Paris	June 27 / 28
Interim Report 2011	August 4
UBS Best of Germany Conference, New York	September 14 / 15
Nine-month Report 2011	November 8
TMT Conference Morgan Stanley, Barcelona	November 16 - 18
German Equity Forum Fall 2011	Novemer 21 - 23

Segment Reporting 2010 continuing operations

in € million		Lithography	Substrate Bonder	Photomask Equipment	Others	Total
Order Intake						
	2010	118.9	23.6	39.0	7.8	189.3
	2009	73.0	18.8	--	4.5	96.3
Revenue						
	2010	88.9	24.7	18.4	7.0	139.1
	2009	77.6	18.3	--	8.0	103.9
Segment-EBIT						
	2010	17.0	-7.1	2.1	2.3	14.3
	2009	11.7	-3.8	--	-5.1	2.8
Segment-EBIT-margin						
	2010	*19.1 %*	*-28.7 %*	*11.4 %*	*32.9 %*	*10.3 %*
	2009	*15.1 %*	*-20.8 %*	*--*	*-63.8 %*	*2.7 %*
Employees as of 12/31						
	2010	324	141	91	60	616
	2009	325	119	--	54	498

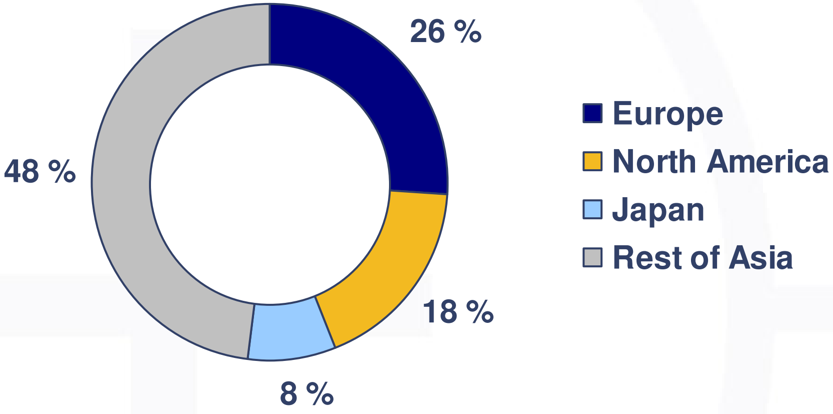
Order Entry Analysis 2010 continuing operations

by Segment



In € million	2010	2009	%
Photomask Cleaning	39.0	--	--
Lithography	118.9	73.0	+ 63 %
Substrate Bonder	23.6	18.8	+ 25 %
Others	7.8	4.5	+ 74 %
Total	189.4	96.3	+ 97 %

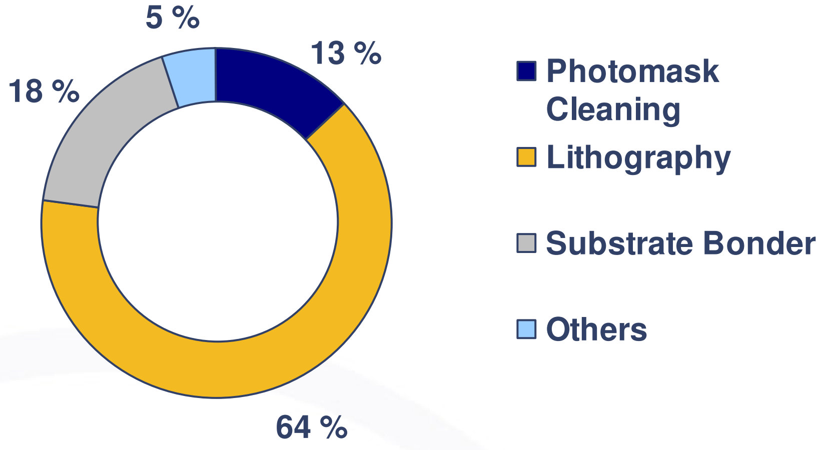
by Regions



in € million	2010	2009	%
North America	33.9	13.0	+ 161 %
Europe	50.0	21.8	+ 129 %
Japan	14.5	4.6	+ 216 %
Rest of Asia	90.9	56.9	+ 60%
Total	189.4	96.3	+ 97 %

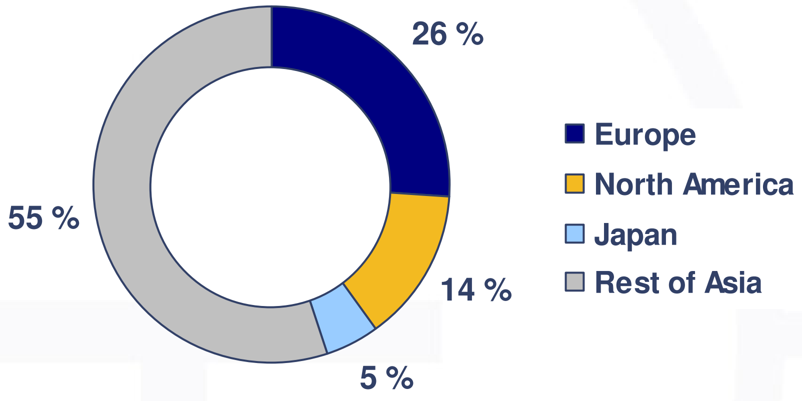
Sales Analysis 2010 continuing operations

by Segment



in € million	2010	2009	%
Photomask Cleaning	18.4	--	--
Lithography	88.9	77.6	+ 15 %
Substrate Bonder	24.7	18.3	+ 35 %
Others	7.0	8.0	- 12 %
Total	139.1	103.9	+ 34 %

by Regions



in € million	2010	2009	%
North America	19.0	21.1	- 10 %
Europe	36.7	30.1	+ 22 %
Japan	6.9	10.5	- 34 %
Rest of Asia	76.5	42.2	+ 81 %
Total	139.1	103.9	+ 34 %

SUSS Management Board

Frank Averdung, CEO

- 1984: Degree in Electrical Engineering from the University of Aachen
- 1985 to 1990: Key Account & Product Marketing Manager, Siemens AG, Munich / Santa Clara, USA
- 1990 to 1992: Corporate Marketing Manager, National Semiconductor
- 1992 to 1995: Marketing Director US & Far East und Head of ITT Semiconductor US, ITT Semiconductors
- 1995 to 1998: General Manager Global Business Operations Siemens, Applied Materials
- 1998: General Manager Central Europe & Eastern Europe, Applied Materials
- 1999 to 2003: Managing Director Europe, ETEC
- 2003 to 2006: Managing Director, NaWoTec GmbH
- 2005 to 2009: Managing Director, Carl Zeiss SMS GmbH und President & General Manager, Carl Zeiss SMT Inc.
- CEO of SUSS MicroTec AG since February 1, 2009

Michael Knopp, CFO

- 1995: Degree in Business Administration (finance and accounting majors) from the University of Bayreuth
- 1995 to 1996: Associate, Wollert-Elmendorff Deutsche Industrie Treuhand GmbH (Deloitte & Touche)
- 1996 to 1997: Financial Analyst, Sensormatic GmbH, Ratingen
- 1997 to 1999: Corporate Investments, Gerresheimer Glas AG, Düsseldorf
- 1999 to 2005: Commercial Director and then CFO (2001–2005), REALTECH AG (IT consulting and software company), Walldorf
- 2005 to 2007: Commercial Director and then Managing Director, Kemmax GmbH (chemical trading and logistics company), Essen
- Member of the Board since August 1, 2007

Strategic Restructuring Measures

Readjustments of Product Lines

- Sold loss making Test Systems division
- Acquired HamaTech APE
- Relocated the Substrate Bonder Division from the US to Germany

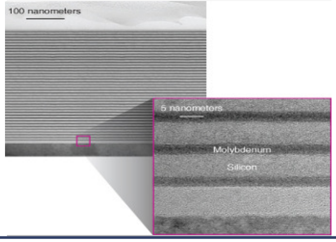
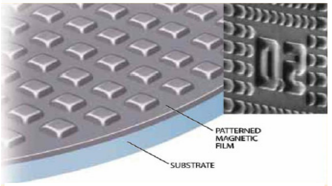
Consolidation of Production Sites

- From four at the beginning of 2010 to two by Q1, 2011
- Moved three product lines under one roof in Sternenfels
- Established Sternenfels as the main SUSS production site

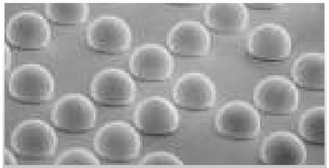
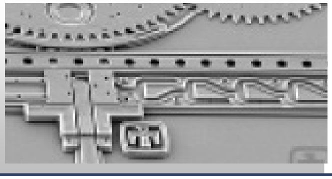
Resizing of Field Offices to Meet Current and Future Business Requirements

- Closed Bangkok office
- Reduced size of the Japan office
- Increased Taiwan and China organizations
- Consolidated „Rest of Asia" in Singapore
- Opened office in DongTan, Korea
- Moved US sales and service organization to Silicon Valley

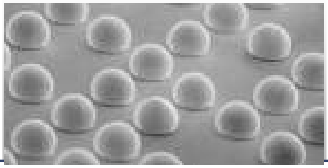
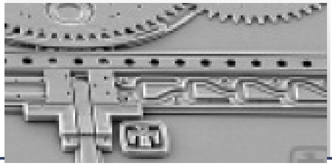
Photomask / NIL Markets & Technologies

Market		Market Growth	SUSS Technologies
Optical Lithography 193i 3x/2x/1x nm		↗	***Photomask Blank Production:*** - Cleaning ***Patterned Photomask Production:*** - Post Exposure Bake, Develop, Wet Etch, Strip, Cleaning ***Photomask In-Fab Usage:*** - Re-cleaning, Pellicle Glue Removal
EUV Lithography < 22nm		↗	***Photomask Blank Production:*** - Cleaning ***Patterned Photomask Production:*** - Post Exposure Bake, Develop, Cleaning ***Photomask In-Fab Usage:*** - In-Fab / Re-cleaning
Nano Imprint Lithography		↑	***CMOS based Templates for Flash Memory:*** - Print Master & Replica cleaning ***Hard Drive Disk Patterned Media:*** - Re-Cleaning

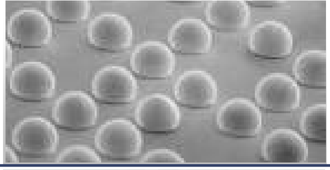
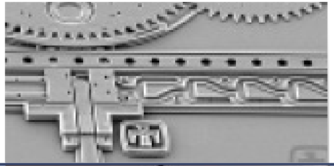
Aligner Markets & Technologies

Market		Market Growth	SUSS Aligner Technologies
Adv. Packaging		↑	***High Accuracy Thick Resist Lithography:*** - Solder-Bumping, Micro-Bumping, Copper Pillar - Passivation Layers - - Redistribution Lithography (RDL) - - Fanout WLP, Embedded Die WLP
3D Integration		↗	***Backside Processing:*** Backside and Infrared Alignment for backside redistribution ***3D RDL and TSV formation:*** - Via Patterning - - Micro-Bumping - - fine pitch RDL
MEMS		↗	***3D Lithography over topography*** ***Thin and Thick Resist lithography*** - Etch Mask, Plating molds, etc. ***Nano imprinting for BioMEMS***
LED		↑	***Patterned Sapphire Substrate Lithography*** ***LED Front End Litho:*** Metal Line-, Contact Pad Formation, Mesa etch masks; ***Nano Imprinting:* Photonic crystal formation** ***Wafer Level Packaging of LED***

Coater / Developer Markets & Technologies

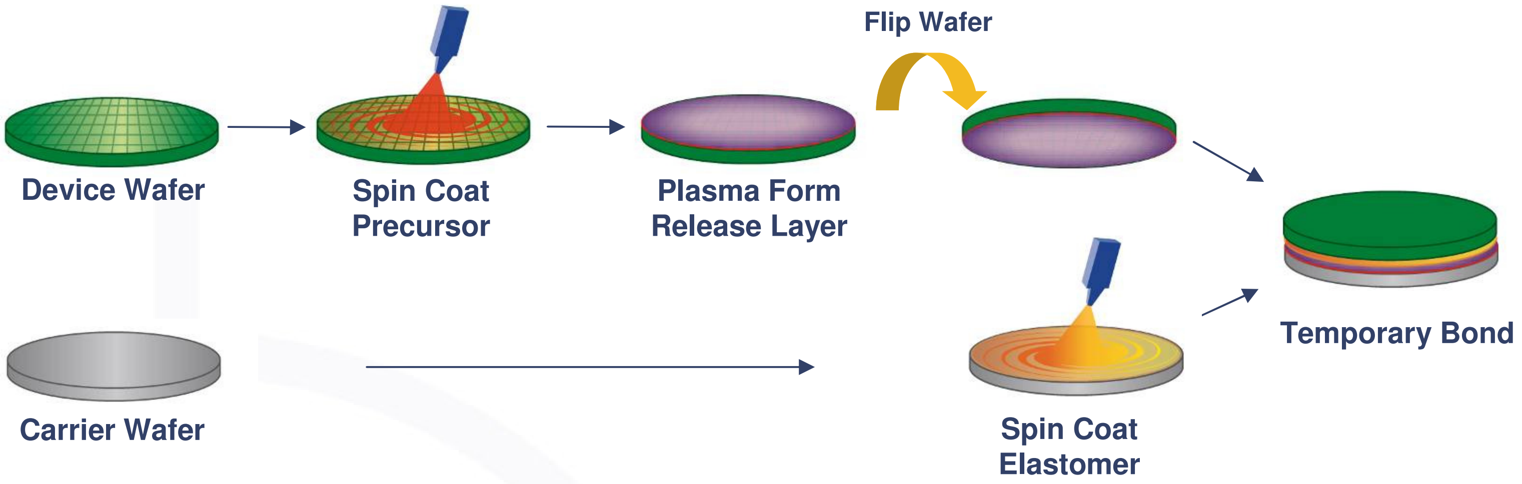
Market		Market Growth	SUSS Coater / Developer Technologies
Adv. Packaging		↗	***Thick Resist:*** - Solder-Bumping, Micro-Bumping, Copper Pillar - Passivation Layers -Redistribution Lithography (RDL)
3D Integration		↑	***Adhesives:*** Thin Wafer Handling / Temporary Bonding as Enabler for Die Stacking / 3D Integration ***Thin and Thick Resist:*** - Via Patterning -- Micro-Bumping
MEMS		↗	***Spray Coating for High Topographies, Thin and Thick Resist:*** - Etch Mask-, Metal Line-, Contact Pad Formation - Negative Resist for Lift-Off
LED		↗	***Thin and Thick Resist:*** - Metal Line-, Contact Pad Formation - Negative Resist for Lift-Off - Litho-Cluster for Maximum Yield

Bonding Markets & Technologies

Market		Market Growth	Current Technology	Future Technology
Adv. Packaging		↗	Metal Bonding Eutectic Bonding	Metal Bonding
3D Integration		↑	Adhesive Bonding	Adhesive Bonding Metal Bonding Fusion Bonding
MEMS		↗	Glass Frit Bonding Eutectic Bonding Fusion Bonding	Fusion Bonding Eutectic Bonding
LED		↗	Metal Bonding	Adhesive Bonding Metal Bonding

Thin Wafer Handling with SUSS Equipment

Temporary Bond



Debond